



UPDATE CHANGE NOTIFICATION # 16790D1Generic Copy

Issue Date: 27-Sep-2012

TITLE: Request for approval to use an alternate production site of wafer fabrication (Update Notification to FPCN16790DA/DB).

PROPOSED FIRST SHIP DATE: Starting on 15 Jan. 2013 until 30 Jan. 2013 (the actual ship date will be different by each product, please check the responsible Sales person).

AFFECTED CHANGE CATEGORY(S): Wafer Fabrication Location Change

SAMPLES: Contact your local ON Semiconductor Sales Office or Akira.Yoneyama@onsemi.com

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Toshikazu.Hirai@onsemi.com

NOTIFICATION TYPE:
Update Change Notification (IPCN)

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

FPCN16790DA/DB announced ON semiconductor-Sanyo Division intention to transfer products from the Sanyo wafer fabrication site located in Sanyo Semiconductor Manufacturing Co., Ltd-SSMC Gifu Japan to the United Microelectronics Corporation Japan-UMCJ wafer fab.

Due to the current economic climate, especially in Japan, we are sorry to unexpectedly inform you that the Board of Directors of UMC Japan (the "Company") resolved on August 21, 2012 to suspend the Company's business and commence preparations for the dissolution and liquidation of the Company.

UMCJ will continue to operate, as is, until it completes the manufacture of the products for the final orders. We are currently working on transferring some products to other manufacturing locations and negotiating bridge inventory levels for those devices.

This update notification is to notify our customers that we are adding an alternate wafer fabrication site to minimize the impact on your production.

No design changes will be made and UMCT manufacturing process and procedures will be the same as UMCJ's. There will be no changes in device functionality, specification and electrical characteristics. Reliability will continue to meet or exceed ON Semiconductor's highest standards.



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Alternate production site

Alternate production site of Wafer fabrication

Production: UMCT (United Microelectronics Corporation Taiwan)

Location: No. 3, Li-Hsin 2nd Rd., Hsinchu Science Park, Hsinchu, Taiwan, R.O.C.

Qualification PLAN

Estimated Date for Qualification Completion: starting November 2012 till March 2013, dependent of the process/product.

Samples should be available after completion of Qualification.

Reliability Test Plan

Test Items	Test Condition	Test Time	
High Temperature Storage	Tstg max	1000	h
Temperature Humidity Storage	Ta=85°C,RH=85%	1000	h
Steady State Operating Life	Tch,Tjmax	1000	h
High Temperature Revers Bias	Tstg rmax,(VDSSmax,VCESmax,VRmax)	1000	h
Temperature Cycle	Ta=Tstg min to max,30min each	200	Cycle
Pressure Cooker (Autoclave)	Ta=121degC,RH=100%,2.03×10 ⁶ Pa	50	h
Soldering Test	260degC,10s(Soldering bath)	1	time

Notice)

List of affected parts:

CPH6341-TL-E
CPH6350-TL-E
ECH8601M-TL-H
ECH8651R-TL-H